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TPS65982EVM TIDA-00714

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB1	1	10.00	Printed Circuit Board		HVL117	Any		
C1, C4	2	10uF	CAP, CERM, 10 µF, 25 V, +/- 20%, X5R, 0603	0603				
C2, C12	2	0.1uF	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0201	0201	CL03A104KP3NNNC	Samsung		
C3	1	0.22uF	CAP, CERM, 0.22 µF, 6.3 V, +/- 20%, X5R, 0201	0201	GRM033R60J224ME90	MuRata		
C5	1	0.1uF	CAP, CERM, 0.1 μF, 50 V, +/- 20%, C0G/NP0, 0402	0402	C1005X7R1H104M	TDK		
C6	1	1uF	CAP, CERM, 1 µF, 35 V, +/- 10%, JB, 0402	0402	C1005JB1V105K050BC	TDK		
C7, C8, C9, C10	4	0.01uF	CAP, CERM, 0.01 μF, 50 V, +/- 10%, X7R, 0402	0402	GRM155R71H103KA88	MuRata		
C11	1	22uF	CAP, CERM, 22 μF, 10 V, +/- 20%, X5R, 0603	0603	GRM188R61A226ME15	MuRata		
C13, C16, C17, C18	4	1uF	CAP, CERM, 1 µF, 10 V, +/- 20%, X5R, 0201	0201	CL03A105MP3NSNC	Samsung		
C17, C16	1	10uF	CAP, CERM, 10 μF, 10 V, +/- 20%, X5R, 0402	0402	CL05A106MP5NUNC	Samsung		
C15, C19	2	220pF	CAP, CERM, 220 pF, 25 V, +/- 10%, X7R, 0201	0201	GRM033R71E221KA01	MuRata		
C20, C23, C26, C31, C34, C37, C42, C45,	9	0.1uF	CAP, CERM, 0.1uF, 50V, +/-20%, C0G/NP0, 0402	0402	C1005X7R1H104M	TDK		
C48 C22, C33, C44	3	10uF	CAP, CERM, 10 μF, 25 V, +/- 10%, X5R, 0805	0805	C2012X5R1E106K125A B	TDK		
C24, C25, C35, C36, C46, C47	6	22uF	CAP, CERM, 22 μF, 35 V, +/- 20%, X5R, 0805	0805	C2012X5R1V226M125A C	TDK		
C28	1	330pF	CAP, CERM, 330 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402	C1005C0G1H331J	TDK		
C29	1	5600pF	CAP, CERM, 5600 pF, 50 V, +/- 10%, X7R, 0402	0402	GRM155R71H562KA88	MuRata		
C39	1	100pF	CAP, CERM, 100 pF, 50 V, +/- 10%, X7R, 0402	0402	CC0402KRX7R9BB101	Yageo America		
C40	1	2200pF	CAP, CERM, 2200 pF, 50 V, +/- 10%, X5R, 0402	0402	GRM155R61H222KA01	MuRata		
C50	1	91pF	CAP, CERM, 91 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402	GRM1555C1H910JA01	MuRata		
C51	1	1800pF	CAP, CERM, 1800 pF, 50 V, +/- 10%, X7R, 0402	0402	GRM155R71H182KA01	MuRata		
C53	1	0.01uF	CAP, CERM, 0.01 μF, 10 V, +/- 10%, X5R, 0201	0201	GRM033R61A103KA01	MuRata		
D1	1	40V	Diode, Schottky, 40 V, 3 A, SMA	SMA	B340A-13-F	Diodes Inc.		
D2, D3, D4, D5, D6, D7, D8, D9	8	White	LED, White, SMD	0402, White	LW QH8G-Q2S2-3K5L- 1	OSRAM		
J1	1		Connector, Receptacle, USB Type C, R/A, SMT	Connector, Receptacle, USB Type C, SMT	20-0000016-01	Lintes Technology		
J2, J3	2		Receptacle, 100mil, 10x2, Gold, TH	10x2 Receptacle	PPPC102LFBN-RC	Sullins Connector Solutions		
J4	1		Connector, DC Power Jack, R/A, 3 Pos, TH	Power connector	JPD1135-509-7F	Foxconn		
J6	1		Header, 100mil, 2x1, Tin, TH	Header 2x1	90120-0122	Molex		
L1	1	21 ohm	Ferrite Bead, 21 ohm @ 100MHz, 6A, 0805	0805	FBMJ2125HM210NT	Taiyo Yuden		
L2, L3, L4	3	10uH		7.2 mm x 6.65 mm	ASPI-0630LR-100M-T15	ABRACON	-	-
Q1, Q2	2	30V	MOSFET, N-CH, 30 V, 60 A, SON 3.3x3.3mm	SON 3.3x3.3mm	CSD17309Q3	Texas Instruments		None

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Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
Q3, Q4, Q5,	8	50 V	Transistor, NPN, 50 V, 0.05 A, SOT-323	SOT-323	DTC114EUAT106	Rohm		
Q6, Q7, Q8,								
Q9, Q10								
R1	1	0.01	RES, 0.01 ohm, 1%, 0.25W, 0805	0805	WSL0805R0100FEA18			
R3, R5,	16	0	RES, 0, 5%, 0.05 W, 0201	0201	ERJ-1GE0R00C	Panasonic		
R10, R11, R38, R39,								
R40, R41,								
R46, R56,								
R60, R62,								
R65, R66,								
R69, R71								
R4, R7, R8,	4	3.3k	RES, 3.3 k, 5%, 0.063 W, 0402	0402	CRCW04023K30JNED	Vishay-Dale		
R9						•		
R12, R13,	9	1.00k	RES, 1.00 k, 1%, 0.05 W, 0201	0201	CRCW02011K00FKED	Vishay-Dale		
R14, R15,								
R27, R42,								
R43, R44,								
R45	-	2 021-	DEC 2.02 I. 40/ 0.05 W 2224	0004	CDC/M00040/C05/C5	Vieles Dele		
R20, R75,	5	3.83k	RES, 3.83 k, 1%, 0.05 W, 0201	0201	CRCW02013K83FKED	Vishay-Dale		
R76, R79,								
R80 R21, R24,	10	100k	RES, 100 k, 1%, 0.05 W, 0201	0201	CRCW0201100KFKED	Vishay-Dale		
R25, R26,	10	TOOK	11LS, 100 K, 170, 0.03 W, 0201	0201	CROWOZOTTOOKI KED	Visitay-Date		
R29, R33,								
R49, R52,								
R55, R70								
R28	1	15.0k	RES, 15.0 k, 1%, 0.063 W, 0402	0402	CRCW040215K0FKED	Vishay-Dale		
R72, R73,	8	560	RES, 560, 5%, 0.063 W, 0402	0402	CRCW0402560RJNED	Vishay-Dale		
R74, R86,								
R87, R89,								
R90, R96								
R77, R78	2	9.09k	RES, 9.09 k, 1%, 0.05 W, 0201	0201	CRCW02019K09FKED	Vishay-Dale		
R82, R92,	3	100k	RES, 100 k, 1%, 0.063 W, 0402	0402	CRCW0402100KFKED	Vishay-Dale		
R102		32.4k	RES, 32.4 k, 1%, 0.063 W, 0402	0402	CRCW040232K4FKED	Vielen Dele		
R84 R85	1	32.4k 2.74k	RES, 2.74 k, 1%, 0.063 W, 0402	0402	CRCW040232K4FKED	Vishay-Dale Vishay-Dale		
R88, R97,	3	47.5k	RES, 47.5 k, 1%, 0.063 W, 0402	0402	CRCW04022K74FKED	Vishay-Dale Vishay-Dale		
R109	3	47.JK	11LO, 47.5 K, 170, 0.005 W, 0402	0402	CROW040247R3FRED	Visitay-Date		
R94	1	19.1k	RES, 19.1 k, 1%, 0.063 W, 0402	0402	CRCW040219K1FKED	Vishay-Dale		
R95	1	8.45k	RES, 8.45 k, 1%, 0.063 W, 0402	0402	CRCW04028K45FKED	Vishay-Dale		
R104	1	7.15k	RES, 7.15 k, 1%, 0.063 W, 0402	0402	CRCW04027K15FKED	Vishay-Dale		
R108	1	9.53k	RES, 9.53 k, 1%, 0.063 W, 0402	0402	CRCW04029K53FKED	Vishay-Dale		
S1	1		DIP Switch, SPST 4Pos, Slide, SMT	6.2x2.0x6.2mm	TDA04H0SB1	C&K Components		
S3	11		SWITCH TACTILE SPST-NO 0.05A 12V	3x1.6x2.5mm	B3U-1000P	Omron Electronic Component		
TP1, TP2,	5		Test Point, Miniature, SMT	Test Point, Miniature,	5019	Keystone	1	
TP3, TP4,				SMT			1	
TP5			OV OMET OF STREET MANY STREET TO STREET	0010.0	MOTOGODY (ONLO	WC drawd		
U1	1		3V, 8Mbit, Serial Flash Memory with Dual and Qual SPI, SOIC-8	SOIC-8	W25Q80DVSNIG	Winbond		
U2	1		TPS65982 Preview Specification, ZQZ0096A	ZQZ0096A	TPS65982AAZQZR	Texas Instruments		Texas Instruments
U3, U4	2		1, 4, 6 CHANNEL PROTECTION SOLUTION FOR	DQA0010A	TPD4E05U06DQA	Texas Instruments		None
30, 04	_		SUPER-SPEED (UP TO 6 GBPS) INTERFACE,	D 30 1001	TI DIEGOOODQA	Toxac instruments		11010
			DQA0010A					
U5, U6, U7	3		4.5V to 28V Input, 3A Output, Synchronous SWIFT	DRC0010J	TPS54335DRCR	Texas Instruments	TPS54335DRCT	Texas Instruments
, -	•		Step-Down DC-DC Converter, DRC0010J					
C27, C30,	0	120pF	CAP, CERM, 120 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402	GRM1555C1H121JA01	MuRata		
C38, C41,					D			
C49, C52								

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
FID1, FID2,	0		Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A		
FID3, FID4,								
FID5, FID6								
H1, H2, H3,	0		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips	Screw	NY PMS 440 0025 PH	B&F Fastener Supply		
H4			panhead					
H5, H6, H7,	0		Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Keystone		
H8								
J5	0		Receptacle, 100mil, 3x1, Gold, TH	,	PPPC031LFBN-RC	Sullins Connector Solutions		
				2.54mm, TH				
J7	0		Header, 100mil, 2x2, Tin, SMT	2x2 100mil Tin	15-91-2040	Molex		
				Header				
R2, R6,	0	0	RES, 0, 5%, 0.05 W, 0201	0201	ERJ-1GE0R00C	Panasonic		
R16, R17,								
R18, R19,								
R22, R23,								
R30, R31,								
R32, R34,								
R35, R36,								
R37, R47,								
R48, R50,								
R51, R53,								
R54, R57,								
R58, R59,								
R61, R63,								
R64, R67,								
R68	_	2001-	DEC 200 k 50/ 0.002 W 0402	0402	CDC/MO400000K INIED	Viahar Dala		
R81, R91, R101	0	220k	RES, 220 k, 5%, 0.063 W, 0402	040∠	CRCW0402220KJNED	Vishay-Dale		
R83, R93,	0	43.2k	RES, 43.2 k, 1%, 0.063 W, 0402	0402	CRCW040243K2FKED	Vishay-Dale		
R103								
S2	0		DIP Switch, SPST 4Pos, Slide, SMT	6.2x2.0x6.2mm	TDA04H0SB1	C&K Components		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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